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Sommario/riassunto

This completely revised edition remains the only comprehensive treatise on polymer coatings for electronics. Since the original edition, the applications of coatings for the environmental protection of electronic systems have greatly increased, largely driven by the competitive need to reduce costs, weight and volume. The demands for high-speed circuits for the rapid processing of signals and data, high-density circuits for the storage and retrieval of megabits of memory, and the improved reliability required of electronics for guiding and controlling weapons and space vehicles have triggered